

●USP-8B04 Power Dissipation

Power dissipation data for the USP-8B04 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board Dimensions: 76.2mm × 114.3mm (8700mm² in one side)

1st inner layer : 50mm × 50mm_with heat sink

2nd inner layer : 70mm × 70mm_with heat sink

3rd inner layer : 70mm × 70mm_ with heat sink

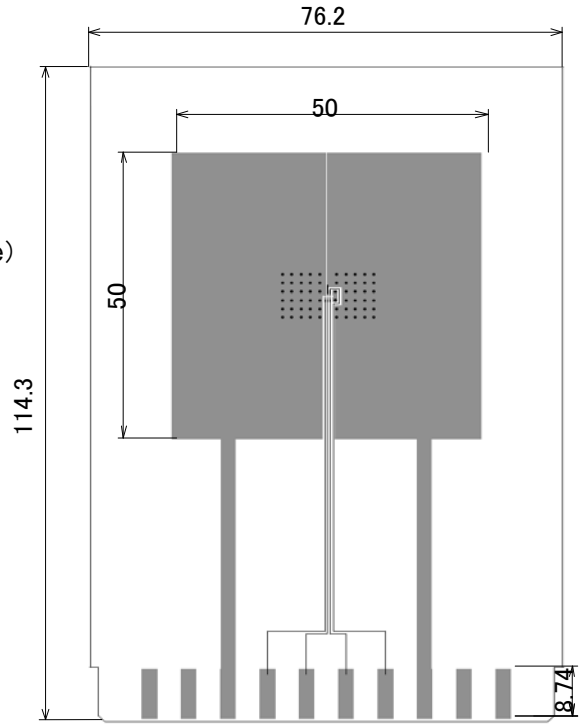
4th inner layer : 50mm × 50mm_with heat sink

Each heat sink back metal is connected to the Inner layers respectively.

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : 60 x 0.2 Diameter / 12 x 0.3 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (T_{jmax}=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	θ_{ja} (°C/W)
25	1000	100.00
85	400	

